

Invited Speech:

The Next 50 Billion Chips – Innovation Through Partnership



Mr. Tim Whitfield

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About the Speaker

Tim Whitfield is Director of Engineering for ARM's Hsinchu Design Centre in Taiwan. He joined ARM in 2000 and was involved with the first ARM synthesisable core, and a founder member of the physical implementation group. Tim technically led a number of CPU macro hardening projects for ARM partners and foundry projects. He has also led a number of key ARM development and test chips used for SW development and IP validation. These developments have spanned multiple process nodes from 180nm to 16nm. Tim moved here three years ago to create a design centre focussed on ARM implementation at advanced process nodes. The design centre is now expanding to include customer support services and the recently announced ARM M-class CPU design team.

Tim Whitfield graduated from Brunel University, UK in 1995 with a degree in Electrical and Electronic Engineering. Prior to join ARM, he worked for GEC and Fujitsu Telecommunications.

Abstract

ARM's business model is built on collaboration and partnership. Earlier this year ARM celebrated the partnership shipping a cumulative 50 billion ARM-powered devices. This presentation will outline the underlying principles of collaboration in the industry and why it is critical to the future success of the industry.